

[54] **DUAL HEAT SINK FOR ELECTRONIC SEMICONDUCTOR DEVICES**

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[**] **Term:** 14 Years

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[51] **Int. Cl.** D13-03

[52] **U.S. Cl.** D13/23

[58] **Field of Search** D13/23; 174/16 HS; 357/81; 165/80, 80 A, 80 B

[56] **References Cited**

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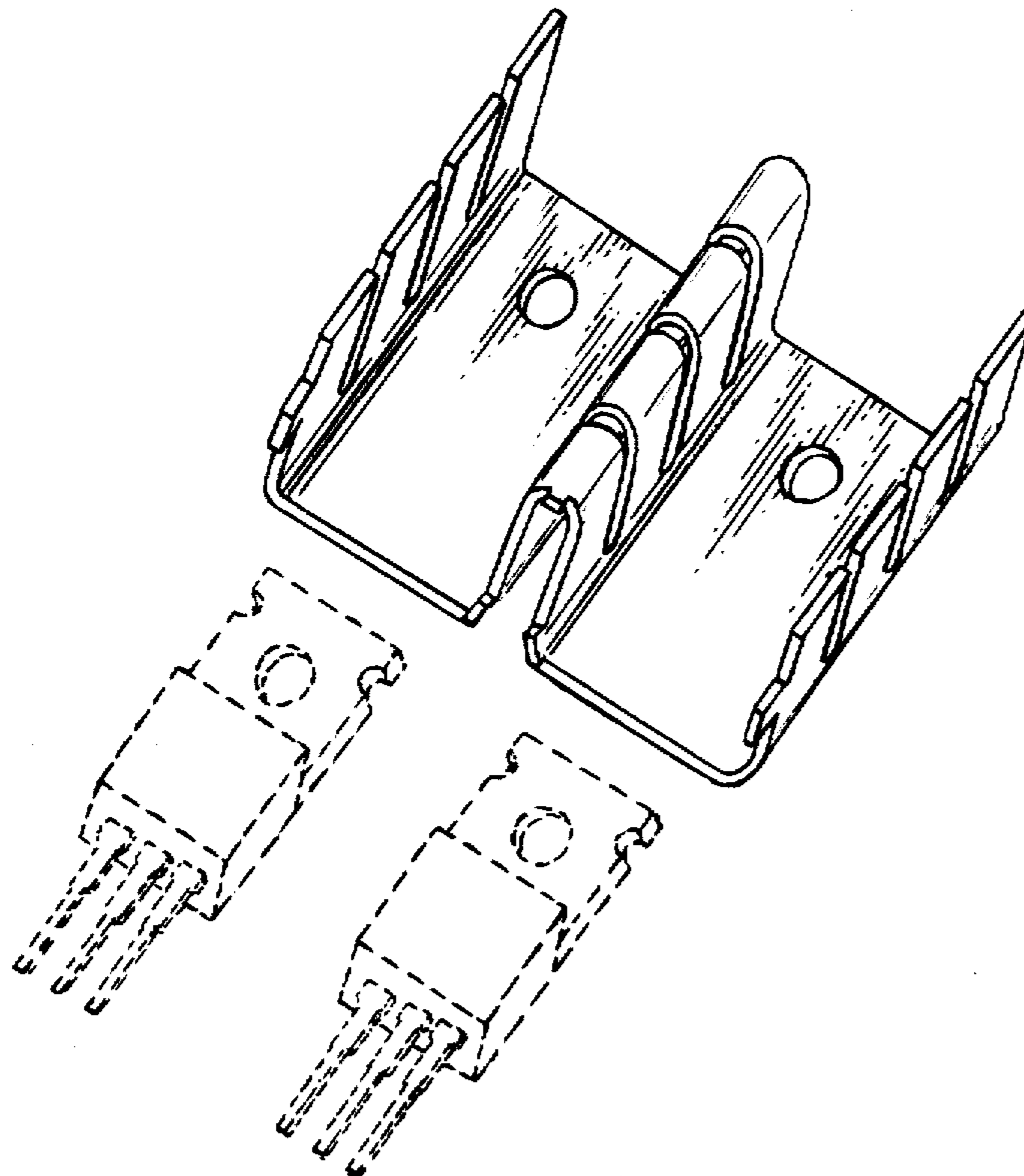
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[57] **CLAIM**

The ornamental design for a dual heat sink for electronic semiconductor devices, substantially as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a dual heat sink for electronic semiconductor devices showing my new design; the broken lines being shown for illustrative purposes, only;
 FIG. 2 is a front elevational view of the same heat sink;
 FIG. 3 is a rear elevational view thereof;
 FIG. 4 is a side elevational view thereof, looking toward the right side of the heat sink as it is shown in FIG. 1;
 FIG. 5 is a side elevational view thereof, looking toward the left side of the heat sink as it is shown in FIG. 1;
 FIG. 6 is a top plan view thereof; and
 FIG. 7 is a bottom plan view thereof.



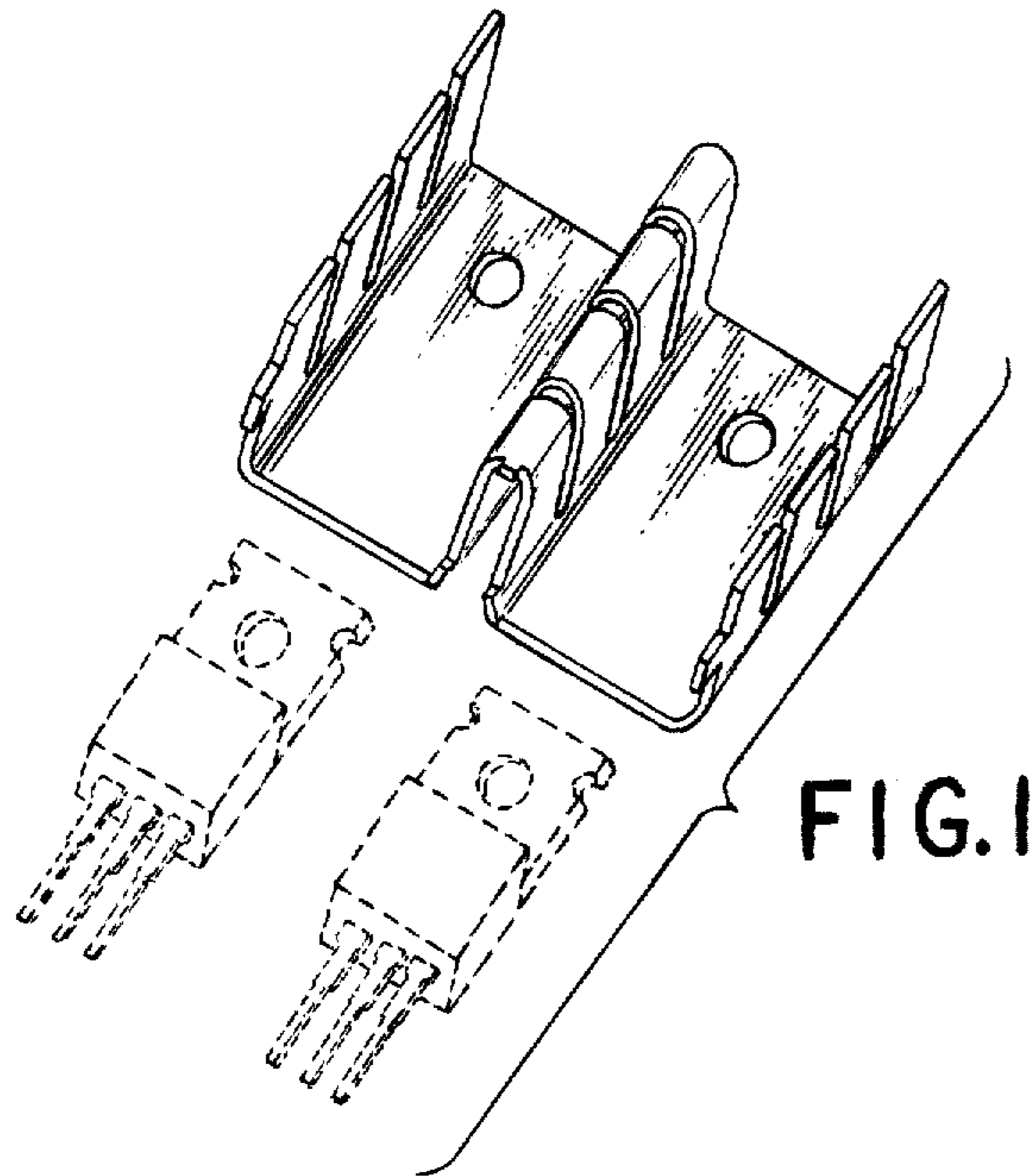


FIG. 1

FIG. 2

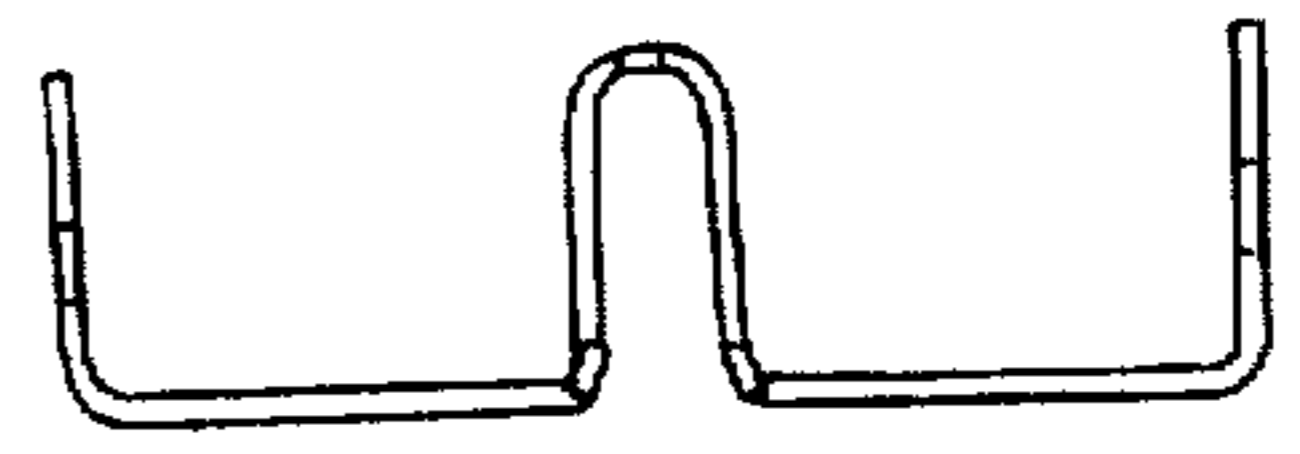


FIG. 3

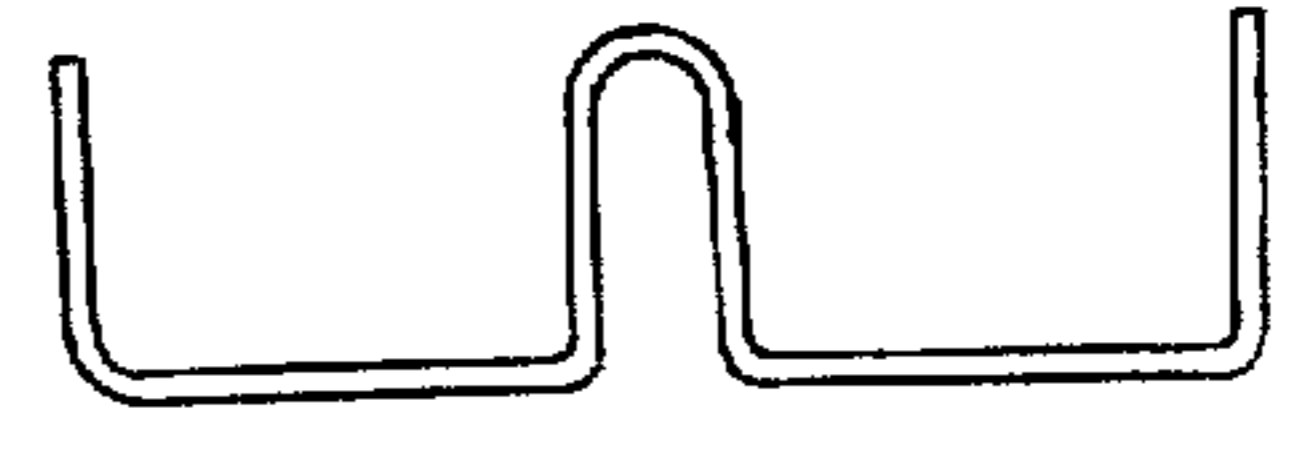


FIG. 4

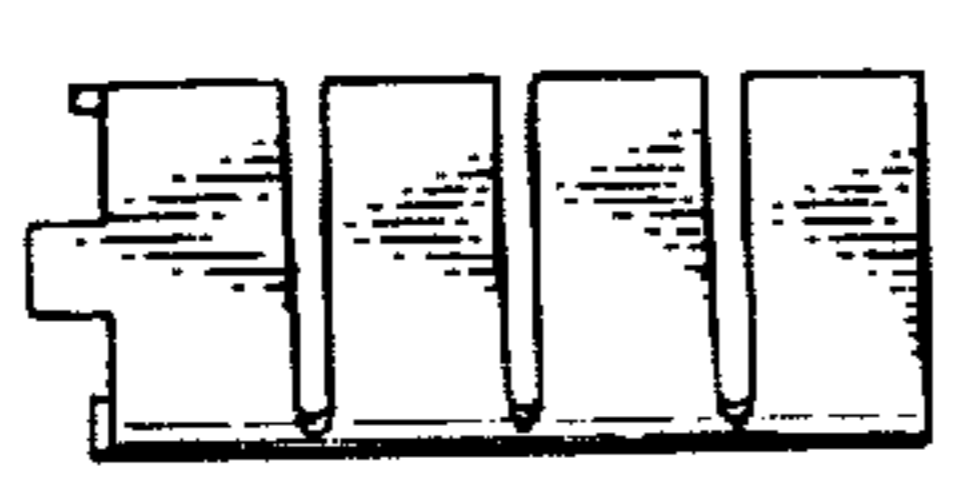


FIG. 5

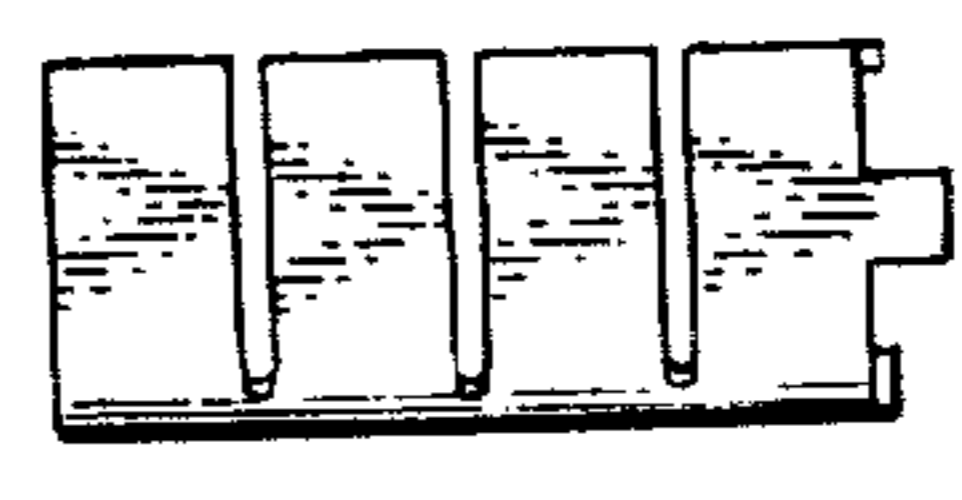


FIG. 6

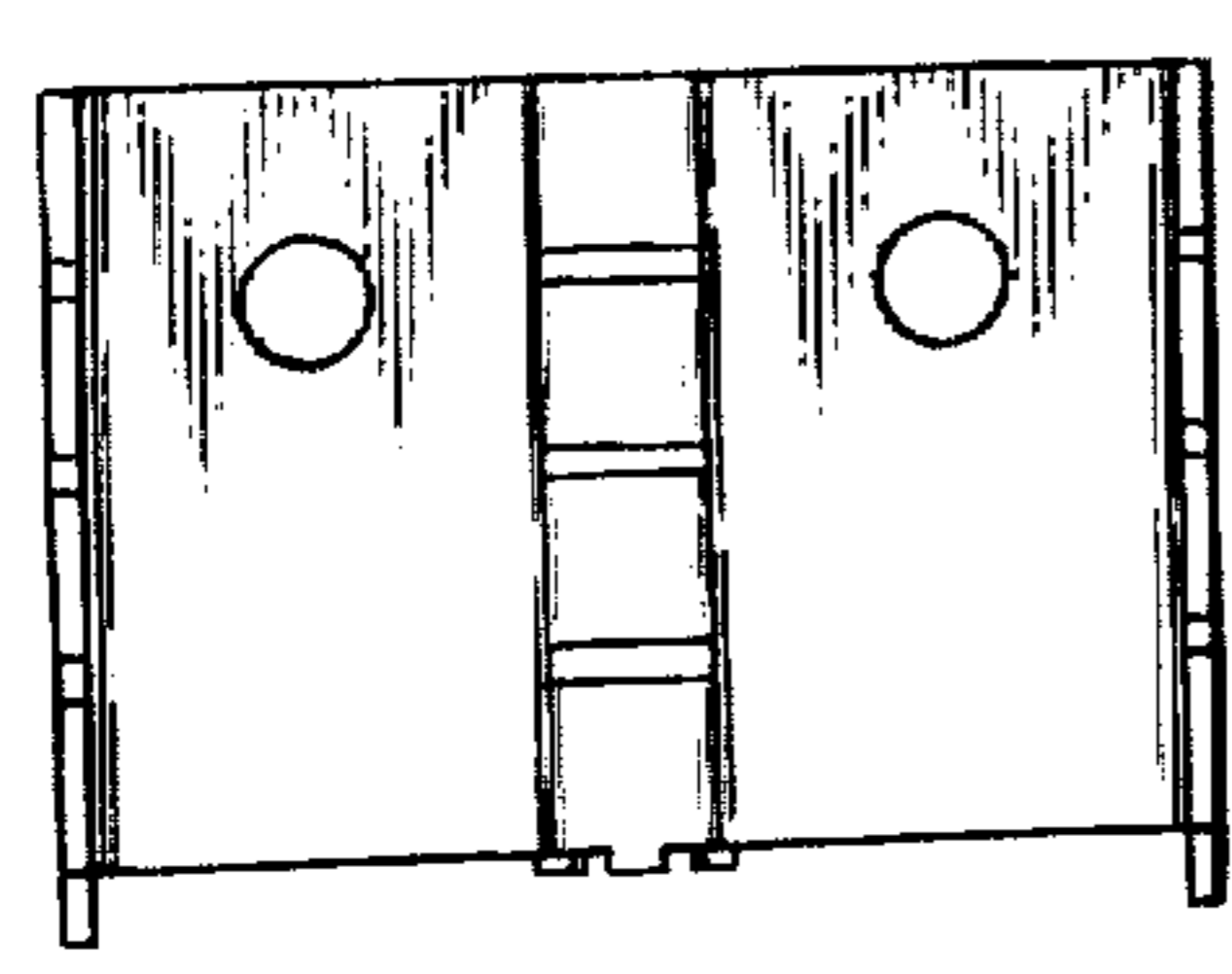


FIG. 7

